L Number	Hits	Search Text	DB	Time stamp
1	330	(pcb substrate (printed adj circuit adj board)) and (thermal adj vias)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 14:10
2	505	(pcb substrate (printed adj circuit adj board)) and (thermal adj (pad vias))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 14:10
3	181	((pcb substrate (printed adj circuit adj board)) and (thermal adj (pad vias))) and (semiconductor near1 (package packaging device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 14:11
4	238	((pcb substrate (printed adj circuit adj board)) and (thermal adj (pad vias))) and (semiconductor chip IC) and (heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 14:12
5	181	(((pcb substrate (printed adj circuit adj board)) and (thermal adj (pad vias))) and (semiconductor near1 (package packaging device))) and (semiconductor chip IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 14:13
6	102	(((pcb substrate (printed adj circuit adj board)) and (thermal adj (pad vias))) and (semiconductor near1 (package packaging device))) and (sealing encapsulating encapsulant encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 14:13
7	13	5942795.URPN.	USPAT	2003/05/16 14:32
8	6	("5710459" | "5736781" | "5773882" | "5777387" | "5789810" | "5854512").PN.	USPAT	2003/05/16 14:33

L Number	Hits	Search Text	DB	Time stamp
85	51	"5835988"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 15:20
86	28	"5986209"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 15:20
87	41	"5554886"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 15:20
88	15	"6002167"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 15:20
89	26	"5760471"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 15:22
90	124	"5835988" "5986209" "5554886" "6002167" "5760471"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/16 15:22
91	1	6404046.URPN.	USPAT	2003/05/16 15:33
92	41	("3838984" | "4159221" | "4398235" | "4833568" | "4956694" | "4996587" | "5068713" | "5230759" | "5258094" | "5266834" | "5332864" | "5381039" | "5381047" | "5394010" | "5414300" | "5435057" | "5455387" | "5521429" | "5587341" | "5594275" | "5625221" | "5677569" | "5715147" | "5742007" |. "5760471" | "5835988" | "5852320" | "5859471" | "5877043" | "5880403" | "5950074" | "5962810" | "5977613" | "5986209" | "6114221" | "6130115" | "6143981" | "6225146" | "6242281" | "6281568" | "6404046").PN.	USPAT	2003/05/16 15:33
–	30061	((folded near1 flexible near1 substrate) ((flexible ner1 tape) near3 around))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/08 07:18
–	15	(((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/25 07:07
–	128	(((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) not ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/25 07:10
–	35	(((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and chips	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/25 07:13
–	41	(((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (chips die (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/09 13:15
–	144	((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/22 10:01
–	3	"6246114"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/22 10:12

–	19	"5818107"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/22 10:14
–	33	"5394303"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/22 10:17
–	30	FUKAZAWA-NORIO	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/22 10:30
–	8	KAWAHARA-KOICHI	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/22 10:30
–	48	"5394303" "5818107" "6246114"	USPAT	2002/03/22 10:58
–	145	((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/09 13:11
–	12	(((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball) and (rigid reinforc$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/09 13:14
–	15	(((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/08 07:24
–	3	((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball)) not ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball) and (rigid reinforc$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/08 07:24
–	88	(((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (chip device die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/08 07:25
–	41	((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/08 07:26
–	31	((((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber)) not ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/08 07:26
–	23	(folded near1 flexible near1 substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/08 07:27
–	18	((folded near1 flexible near1 substrate)) not ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/08 07:28
–	5921	folded near1 substrate) (flexible near1 tape	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/09 13:12
–	398	(folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/09 13:14
–	240	((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc$4)) and (chip die (integrated adj circuit) (semiconductor adj element))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/09 13:21

–	75	((((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc$4)) and (chip die (integrated adj circuit) (semiconductor adj element)))) and (second near3 (chip die (integrated adj circuit) (semiconductor adj element)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/09 13:30
–	17	"5805422"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/10 08:36
–	15	5805422.URPN.	USPAT	2003/03/10 08:39
–	6	("3427715" | "4922059" | "5148265" | "5148266" | "5229916" | "5394303").PN.	USPAT	2003/03/10 08:39
–	7	6225688.URPN.	USPAT	2003/03/18 12:42
–	5	("4982265" | "5046238" | "5334875" | "5646446" | "5776797").PN.	USPAT	2003/03/18 12:45
–	12	5776797.URPN.	USPAT	2003/03/18 12:45
–	5	("3039177" | "3467892" | "4628408" | "4833568" | "5289346").PN.	USPAT	2003/03/18 14:09
–	57	5289346.URPN.	USPAT	2003/03/18 14:09
–	41305	semiconductor and (stacking stacked)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:37
–	35232	(semiconductor and (stacking stacked)) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:38
–	215	((semiconductor and (stacking stacked)) and (method process)) and ((plexible near1 (tape substrate)) (bonding near tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:42
–	63	(((semiconductor and (stacking stacked)) and (method process)) and ((plexible near1 (tape substrate)) (bonding near tape))) and (bending bended)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:40
–	23	((plexible near1 (tape substrate)) (bonding near tape)) with (bending bended)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:41
–	2	(((semiconductor and (stacking stacked)) and (method process)) and ((plexible near1 (tape substrate)) (bonding near tape))) and (((plexible near1 (tape substrate)) (bonding near tape)) with (bending bended))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:41
–	248	((semiconductor and (stacking stacked)) and (method process)) and (((plexible folded folding) near1 (tape substrate)) (bonding near tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:43
–	16	(US-5805422-$ or US-5394303-$ or US-6225688-$ or US-5776797-$ or US-5646446-$ or US-6246114-$ or US-5818107-$ or US-6528353-$ or US-6473308-$ or US-6462412-$ or US-6441476-$ or US-6300679-$ or US-6262895-$ or US-6121676-$).did. or (US-20010006252-$).did. or (JP-08222691-$).did.	USPAT; US-PGPUB; JPO	2003/03/18 14:43
–	244	(((semiconductor and (stacking stacked)) and (method process)) and (((plexible folded folding) near1 (tape substrate)) (bonding near tape))) not ((US-5805422-$ or US-5394303-$ or US-6225688-$ or US-5776797-$ or US-5646446-$ or US-6246114-$ or US-5818107-$ or US-6528353-$ or US-6473308-$ or US-6462412-$ or US-6441476-$ or US-6300679-$ or US-6262895-$ or US-6121676-$).did. or (US-20010006252-$).did. or (JP-08222691-$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:43

–	2	("6049123" | "6102710").PN.	USPAT	2003/03/18 14:48
–	0	6469377.URPN.	USPAT	2003/03/18 14:49
–	0	6444921.URPN.	USPAT	2003/03/18 14:55
–	44	("3795037" | "4271588" | "4547834" | "4648179" | "4664309" | "4755417" | "4783722" | "4800461" | "4858077" | "4897918" | "4954877" | "4954878" | "5065227" | "5100492" | "5177594" | "5199163" | "5264065" | "5306571" | "5378306" | "5426072" | "5428190" | "5429879" | "5474458" | "5478972" | "5483421" | "5499444" | "5530288" | "5544017" | "5573428" | "5575630" | "5590460" | "5591519" | "5627405" | "5659153" | "5665650" | "5678287" | "5682061" | "5688584" | "5691041" | "5745986" | "6064576" | "6118671" | "6191952" | "6259037").PN.	USPAT	2003/03/18 14:55
–	0	6344683.URPN.	USPAT	2003/03/18 14:58
–	7	("5377077" | "5446620" | "5463253" | "5815372" | "5933712" | "5995379" | "6005292").PN.	USPAT	2003/03/18 14:58
–	10	5933712.URPN.	USPAT	2003/03/18 15:00
–	3	("5432729" | "5466634" | "5578516").PN.	USPAT	2003/03/18 15:02
–	3	("5432729" | "5466634" | "5578516").PN.	USPAT	2003/03/18 15:03
–	5	6121676.URPN.	USPAT	2003/03/18 15:08
–	12	("5008496" | "5229916" | "5345205" | "5783870" | "5790380" | "5805422" | "6014316" | "6061245" | "6121676" | "6172418" | "6177721" | "6208521").PN.	USPAT	2003/03/18 15:09
–	12	6208521.URPN.	USPAT	2003/03/18 15:09
–	0	6486544.URPN.	USPAT	2003/03/18 15:11
–	12	("5159535" | "5450283" | "5578525" | "5646446" | "5773882" | "5783870" | "5949142" | "5969426" | "6071755" | "6075287" | "6208521" | "6324067").PN.	USPAT	2003/03/18 15:11
–	12	("5159535" | "5450283" | "5578525" | "5646446" | "5773882" | "5783870" | "5949142" | "5969426" | "6071755" | "6075287" | "6208521" | "6324067").PN.	USPAT	2003/03/18 15:11
–	3	6281577.URPN.	USPAT	2003/03/18 15:14
–	17	("4983533" | "5006925" | "5016138" | "5224023" | "5313096" | "5345205" | "5397916" | "5448511" | "5514907" | "5602420" | "5604377" | "5648684" | "5656856" | "5754405" | "5790380" | "6121676" | "6208521").PN.	USPAT	2003/03/18 15:14
–	23	5448511.URPN.	USPAT	2003/03/18 15:15
–	4	("3766439" | "5117282" | "5313416" | "5335145").PN.	USPAT	2003/03/18 15:17
–	44	5224023.URPN.	USPAT	2003/03/18 15:19
–	0	6507106.URPN.	USPAT	2003/03/18 15:20
–	2	("5224023" | "5646446").PN.	USPAT	2003/03/18 15:20
–	1	"6507095"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/15 08:13